

## NC32 Gel Flux

### Introduction

NC32 is an excellent no clean gel flux for soldering and rework of surface mount assemblies. NC32 gel flux is formulated to provide clear, colorless residue. NC32 can be used in dispensing, stencil printing and pin transfer applications. NC32 works well with leaded and lead-free alloys. It is also halide and halogen free and contains no intentionally added halogens (zero halogen).

### Attributes

- Stable product with a long stencil / work life.
- Excellent print and dispense characteristics.
- Creates bright and shiny solder joints with a clear flux residue.
- Superior activity offering good solderability on all surface finishes.
- Works well for tin/lead and lead-free solder alloys.
- Halide and halogen free (zero halogens).

Gel Flux Packaging	Part Number	Net Weight (Approximate)
Syringe 10 cc	NC32F10CC	5 grams
Syringe 30 cc	NC32F30CC	15 grams
Jar 150 cc	NC32FJ	90 grams

### Compatible Products

NC120, NC160, NC165 liquid fluxes.  
NL932HF solder paste.

### Storage and Handling

- Shelf life is 1 year when the gel flux is stored between 50 to 90 °F (10 and 32 °C) in a standard warehouse or office environment.
- Store the gel flux sealed inside of the original packaging.

### Application

NC32 gel flux is suitable for use in any electronic soldering application. NC32 is designed for stencil printing, pin transfer, dot dispensing and syringe applications. It can be used as a tacky flux for re-balling BGAs and soldering other components. NC32 is also suitable for touchup and rework soldering.

NC32 should be heated through normal soldering operations like SMT reflow, hand soldering, etc. Use the recommended parameters for that process and the solder alloy used.

### Cleaning

Raw gel flux can be removed from the stencil, squeegee blades, and circuit boards using a variety of commercial cleaners. Isopropyl alcohol (IPA) can also be used.

After heating, no-clean flux residues are designed to be “safe” and do not need to be removed from the circuit board. If removal of the flux residues is desired, then a commercial cleaning agent should be used. Several commercial cleaning agents have been tested and found to be effective. Please contact your cleaning chemical supplier for details.

<b>Safety</b>
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Wear chemically resistant gloves and safety glasses when using gel flux. Avoid contact with the flux and avoid breathing fumes, especially during soldering. Follow the guidelines in the Safety Data Sheet (SDS).

J-STD-004 Standard	Test Method	Result
J-STD-004 classification	J-STD-004 methods	ROLO
Visual appearance	Visual	Clear colorless flux residue
Solids content	IPC 2.3.34	65 to 70% wt
Acid value	IPC 2.3.13	150 to 175 mg KOH / gram flux
Halide ion content (Br, Cl, F, I)	IPC 2.3.28.1	0.0% wt
Halogen content (Br and Cl)	EN 14582, IPC 2.3.28.1	0.0% wt
Halide by silver chromate	IPC 2.3.33	No halides detected
Fluoride by spot test	IPC 2.3.35.1	None detected
Copper mirror	IPC 2.3.32	Low activity
Copper corrosion	IPC 2.6.15	No corrosion
Surface Insulation Resistance (SIR)	IPC 2.6.3.7	Pass > 1.00E+09 ohms
Electro Chemical Migration (ECM)	IPC 2.6.14.1	Pass, increase of 0.4 Log <sub>10</sub> ohms